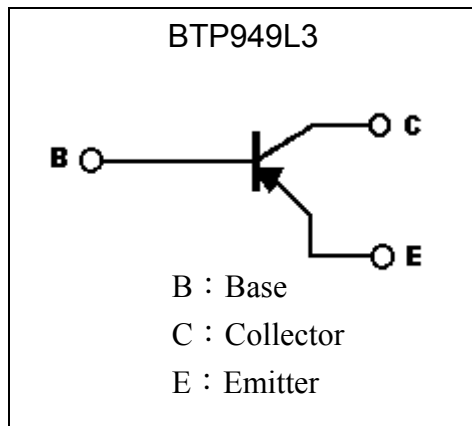
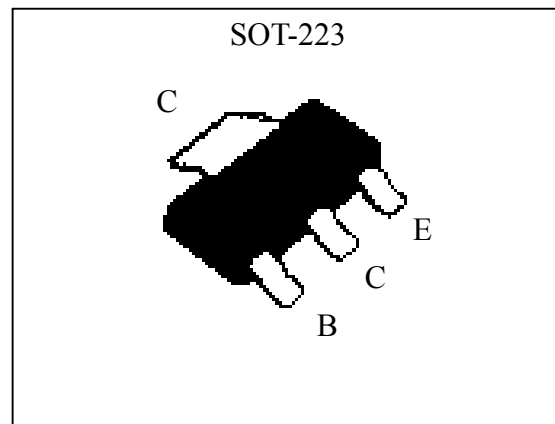


**PNP Epitaxial Planar Power Transistor**

# BTP949L3

**Features**

- Extremely low equivalent on-resistance,  $R_{CE(sat)} = 75m\Omega(max) @ I_C = -3A, I_B = -0.1A$
- 6A continuous current(up to 20A peak)
- Excellent current gain linearity
- Pb-free package

**Symbol**

**Outline**

**Absolute Maximum Ratings** ( $T_a = 25^\circ C$ )

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	$V_{CBO}$	-50	V
Collector-Emitter Voltage	$V_{CEO}$	-30	V
Emitter-Base Voltage	$V_{EBO}$	-6	V
Collector Current (DC)	$I_C$	-5.5	A
Collector Current (Pulse)	$I_{CP}$	-20 (Note 1)	
Power Dissipation @ $T_A = 25^\circ C$	$P_{tot}$	3 (Note 2)	W
Junction Temperature	$T_j$	150	$^\circ C$
Storage Temperature	$T_{stg}$	-55~+150	$^\circ C$

Note : 1. Single Pulse ,  $P_w \leq 380\mu s$ , Duty  $\leq 2\%$ .

2. The power which can be dissipated assuming the device is mounted in a typical manner on a P.C.B. with copper equal to 4 square inch minimum.



**Characteristics (Ta=25°C)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
*BV <sub>CEO</sub>	-30	-	-	V	I <sub>C</sub> =-10mA, I <sub>B</sub> =0
BV <sub>CBO</sub>	-50	-	-	V	I <sub>C</sub> =-100μA, I <sub>E</sub> =0
BV <sub>CER</sub>	-50	-	-	V	I <sub>C</sub> =-1μA, R <sub>BE</sub> ≤1kΩ
BV <sub>EBO</sub>	-6	-	-	V	I <sub>E</sub> =-100μA, I <sub>C</sub> =0
I <sub>CER</sub>	-	-	-50	μA	V <sub>CE</sub> =-40V, R <sub>BE</sub> ≤1kΩ
I <sub>CBO</sub>	-	-	-50	nA	V <sub>CB</sub> =-40V, I <sub>B</sub> =0
I <sub>EBO</sub>	-	-	-10	nA	V <sub>EB</sub> =-6V, I <sub>C</sub> =0
*V <sub>CE(sat)</sub> 1	-	-60	-75	mV	I <sub>C</sub> =-500mA, I <sub>B</sub> =-20mA
*V <sub>CE(sat)</sub> 2	-	-100	-140	mV	I <sub>C</sub> =-1A, I <sub>B</sub> =-20mA
*V <sub>CE(sat)</sub> 3	-	-190	-270	mV	I <sub>C</sub> =-2A, I <sub>B</sub> =-200mA
*V <sub>CE(sat)</sub> 4	-	-380	-440	mV	I <sub>C</sub> =-5.5A, I <sub>B</sub> =-500mA
*V <sub>BE(sat)</sub>	-	-1.1	-1.25	V	I <sub>C</sub> =-5.5A, I <sub>B</sub> =-500mA
*V <sub>BE(on)</sub>	-	-	-1.06	V	V <sub>CE</sub> =-1V, I <sub>C</sub> =-5.5A
*h <sub>FE</sub> 1	100	200	-	-	V <sub>CE</sub> =-1V, I <sub>C</sub> =-10mA
*h <sub>FE</sub> 2	100	200	300	-	V <sub>CE</sub> =-1V, I <sub>C</sub> =-1A
*h <sub>FE</sub> 3	60	80	-	-	V <sub>CE</sub> =-1V, I <sub>C</sub> =-5A
*h <sub>FE</sub> 4	-	10	-	-	V <sub>CE</sub> =-2V, I <sub>C</sub> =-20A
f <sub>T</sub>	-	100	-	MHz	V <sub>CE</sub> =-10V, I <sub>C</sub> =-100mA, f=50MHz
C <sub>ob</sub>	-	122	-	pF	V <sub>CB</sub> =-10V, f=1MHz
t <sub>on</sub>	-	120	-	ns	V <sub>CC</sub> =-10V, I <sub>C</sub> =10I <sub>B1</sub> =-10I <sub>B2</sub> =4A,
t <sub>off</sub>	-	130	-	ns	R <sub>L</sub> =2.5Ω

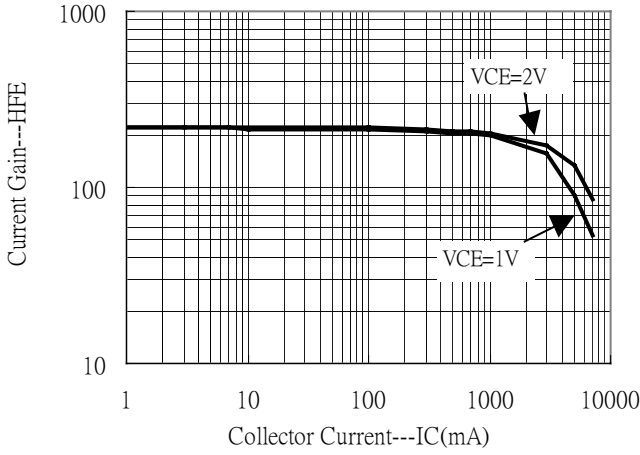
\*Pulse Test : Pulse Width ≤380μs, Duty Cycle≤2%

**Ordering Information**

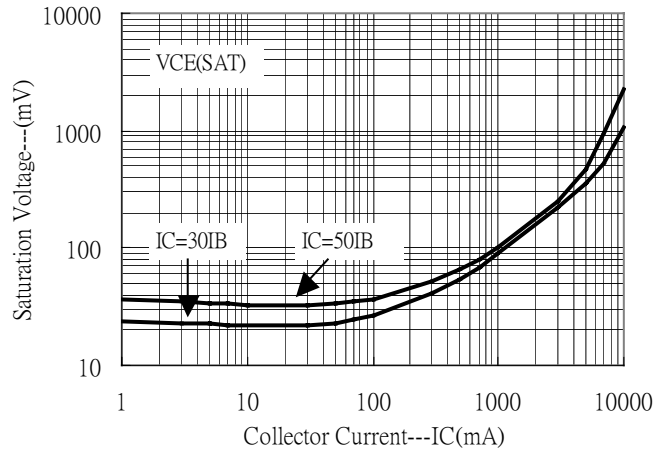
Device	Package	Shipping	Marking
BTN949L3	SOT-223 (Pb-free)	1000 pcs / Tape & Reel	P949

**Characteristic Curves**

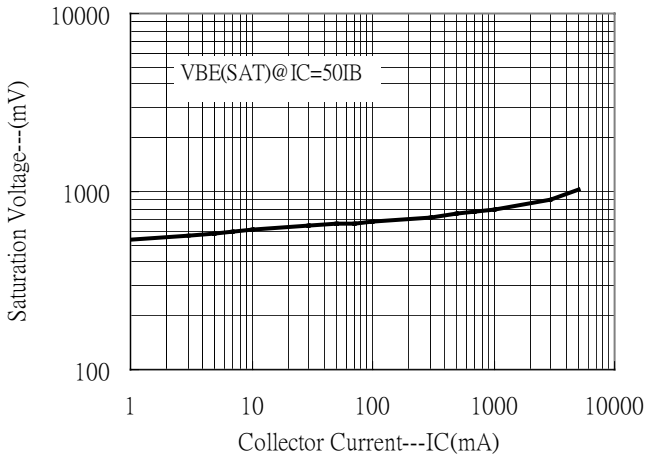
Current Gain vs Collector Current



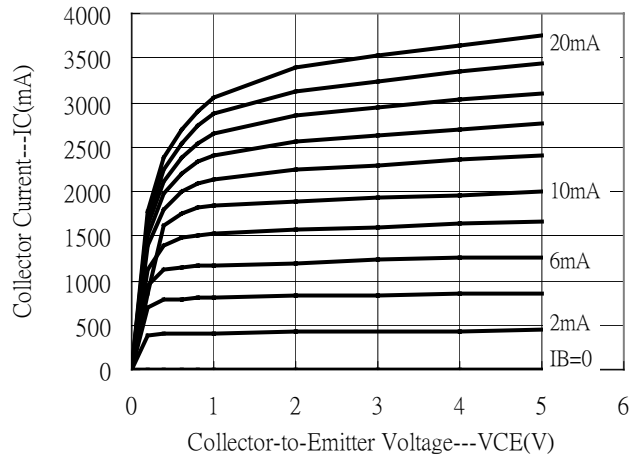
Saturation Voltage vs Collector Current



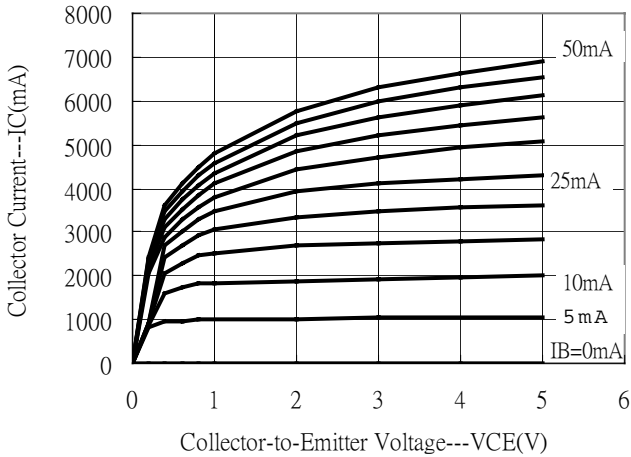
Saturation Voltage vs Collector Current



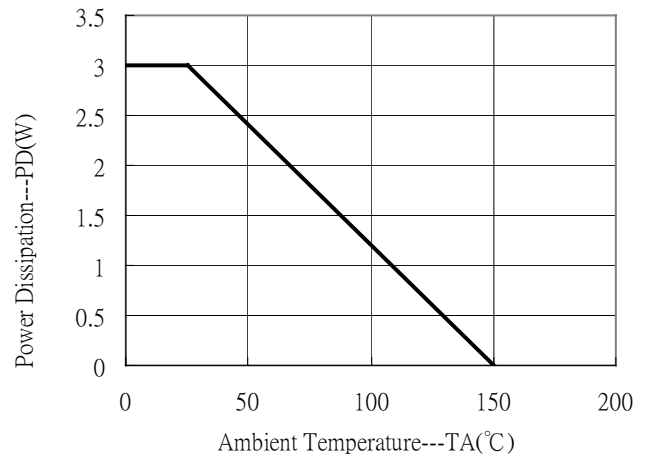
Grounded Emitter Output Characteristics



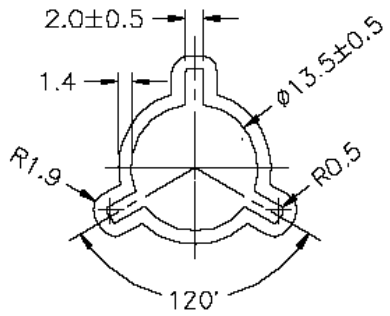
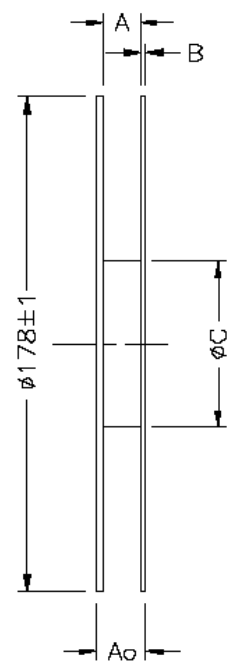
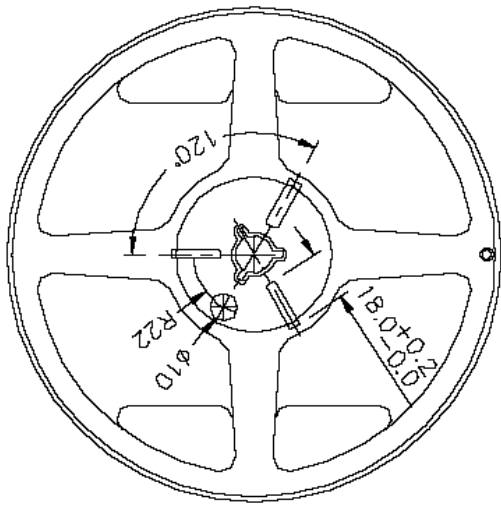
Grounded Emitter Output Characteristics



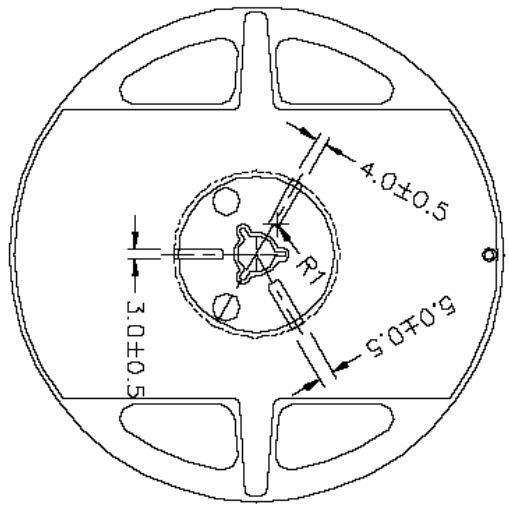
Power Derating Curve



**Reel Dimension**



Width of carrier tape	8	12	16
$A \pm 0.05$	9.0	13.0	17.0
$A_0 \pm 0.05$	12.0	16.0	20.0
B	1.5	1.5	1.5
$\phi C \pm 0$	60	60	60

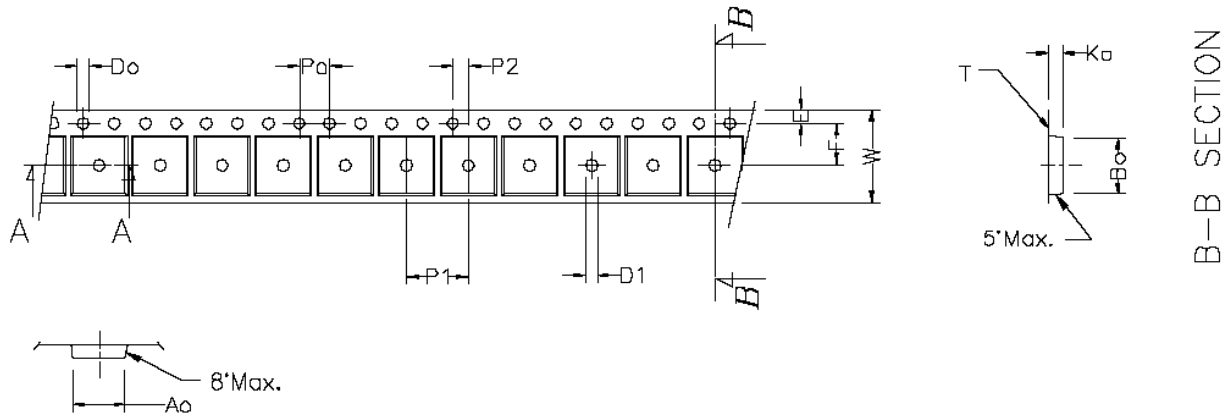


**NOTE :**

1. Material : Anti-static polystyrene.
2. Surface resistivity  $10 \text{ } \Omega\text{m/square}$

**UNIT : millimeter**

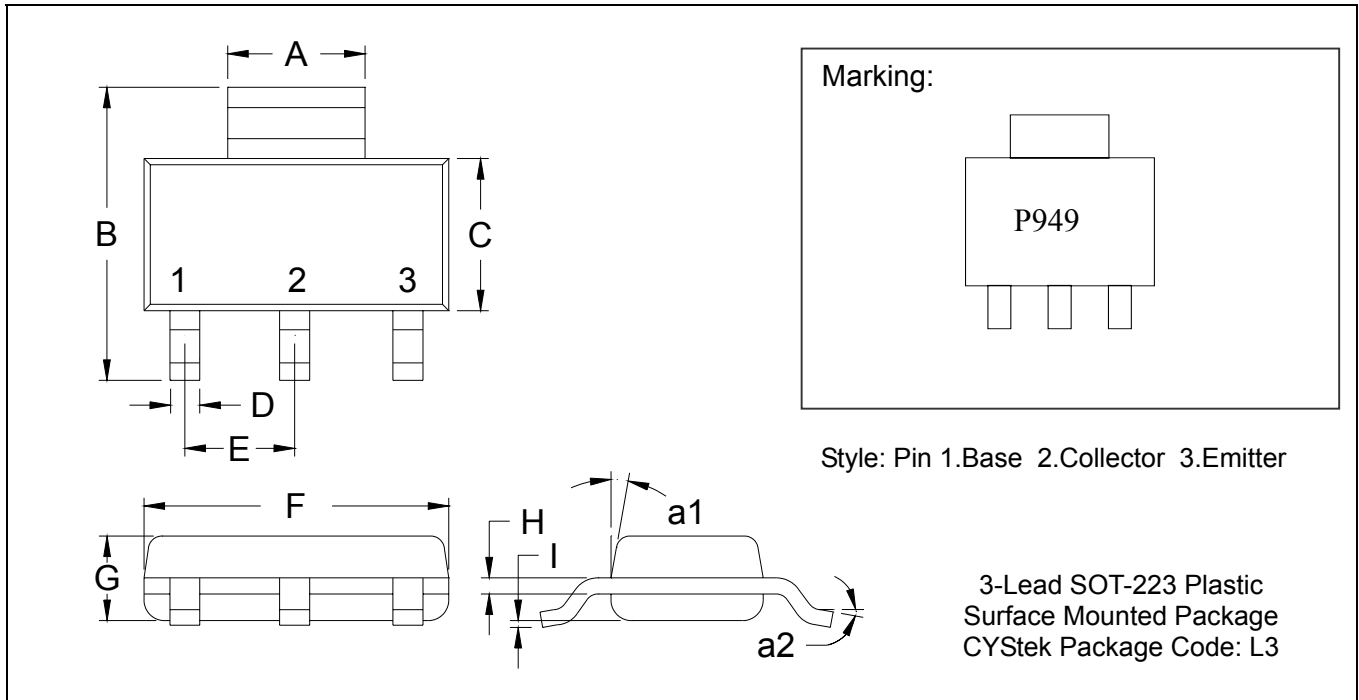
**Carrier Tape Dimension**



A-A SECTION

symbol	$A_o$	$B_o$	$K_o$	$P_o$	$P_1$	$P_2$	$T$
Spec	$6.83 \pm 0.1$	$7.42 \pm 0.1$	$1.88 \pm 0.1$	$4.0 \pm 0.1$	$8.0 \pm 0.10$	$2.0 \pm 0.05$	$0.292 \pm 0.02$
symbol	$E$	$F$	$D_o$	$D_1$	$W$	$10P_o$	
Spec	$1.75 \pm 0.1$	$5.5 \pm 0.05$	$1.60 \pm 0.1$	$1.5 \pm 0.25$	$12.0^{+0.3}_{-0.1}$	$40.0 \pm 0.2$	

**SOT-223 Dimension**



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1142	0.1220	2.90	3.10	G	0.0551	0.0709	1.40	1.80
B	0.2638	0.2874	6.70	7.30	H	0.0098	0.0138	0.25	0.35
C	0.1299	0.1457	3.30	3.70	I	0.0008	0.0039	0.02	0.10
D	0.0236	0.0315	0.60	0.80	a1	*13°	-	*13°	-
E	*0.0906	-	*2.30	-	a2	0°	10°	0°	10°
F	0.2480	0.2638	6.30	6.70					

Notes: 1.Controlling dimension: millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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